relative to 100 parts by mass of the alkali-soluble polyimide (a).

[0084] (Other ingredients)

The photosensitive resin composition of the present invention may further include a crosslinking agent other than the thermally crosslinkable compound (c), a photopolymerization initiator other than the photopolymerization initiator (d), additives such as a polymerization inhibitor, a coloring agent, a surfactant, a silane coupling agent, a titanium chelating agent, a crosslinking accelerator, a sensitizer, a dissolution adjuster, a stabilizer, a defoamer, and a filler and an organic solvent, if necessary.

[0085] Examples of the photopolymerization initiator other than the photopolymerization initiator (d) include oximes, benzophenones, benzylidenes, coumarins, anthraquinones, benzoins, thioxanthones, mercapto compounds, glycine compounds, benzyl dimethyl ketals, α-hydroxyalkylphenones, α-aminoalkylphenones, acylphosphine oxides, and 2,2'-bis(o-chlorophenyl)-4,4',5,5'-tetraphenylbiimidazole. The photosensitive resin composition of the present invention may include two or more of these compounds as the photopolymerization initiator other than the photopolymerization initiator (d).

[0086] Of these compounds, the oximes and the acylphosphine oxides are preferable. Examples of the oximes include 1-phenyl-1,2-butanedione-2-(o-methoxycarbonyl)oxime, 1-phenyl-1,2-propanedione-2-(o-methoxycarbonyl)oxime, 1-phenyl-1,2-propanedione-2-(o-ethoxycarbonyl)oxime, 1-phenyl-1,2-propanedione-2-(o-benzoyl)oxime, bis(α-isonitrosopropiophenoneoxime)isophthal, 1,2-octanedione, 1-